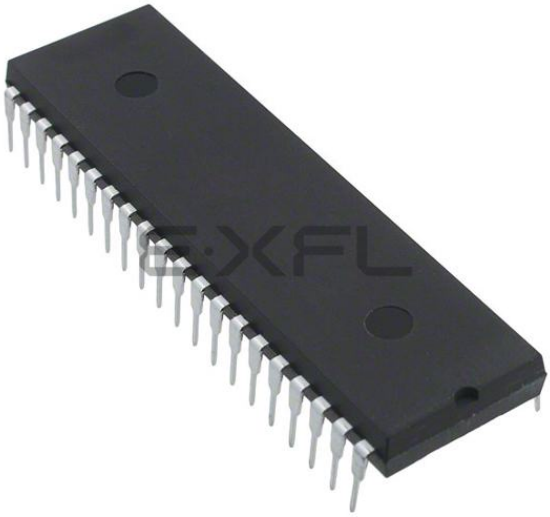

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	25MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	48KB (24K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f4525-e-p

TABLE 1-2: PIC18F2525/2620 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	SPDIP, SOIC			
				PORTA is a bidirectional I/O port.
RA0/AN0	2			
RA0		I/O	TTL	Digital I/O.
AN0		I	Analog	Analog input 0.
RA1/AN1	3			
RA1		I/O	TTL	Digital I/O.
AN1		I	Analog	Analog input 1.
RA2/AN2/VREF-/CVREF	4			
RA2		I/O	TTL	Digital I/O.
AN2		I	Analog	Analog input 2.
VREF-		I	Analog	A/D reference voltage (low) input.
CVREF		O	Analog	Comparator reference voltage output.
RA3/AN3/VREF+	5			
RA3		I/O	TTL	Digital I/O.
AN3		I	Analog	Analog input 3.
VREF+		I	Analog	A/D reference voltage (high) input.
RA4/T0CKI/C1OUT	6			
RA4		I/O	ST	Digital I/O.
T0CKI		I	ST	Timer0 external clock input.
C1OUT		O	—	Comparator 1 output.
RA5/AN4/$\overline{SS}$/HLVDIN/C2OUT	7			
RA5		I/O	TTL	Digital I/O.
AN4		I	Analog	Analog input 4.
$\overline{SS}$		I	TTL	SPI slave select input.
HLVDIN		I	Analog	High/Low-Voltage Detect input.
C2OUT		O	—	Comparator 2 output.
RA6				See the OSC2/CLKO/RA6 pin.
RA7				See the OSC1/CLKI/RA7 pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

TABLE 1-3: PIC18F4525/4620 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTE is a bidirectional I/O port.
RE0/$\overline{RD}$/AN5	8	25	25			
RE0				I/O	ST	Digital I/O.
$\overline{RD}$				I	TTL	Read control for Parallel Slave Port (see also $\overline{WR}$ and $\overline{CS}$ pins).
AN5				I	Analog	Analog input 5.
RE1/$\overline{WR}$/AN6	9	26	26			
RE1				I/O	ST	Digital I/O.
$\overline{WR}$				I	TTL	Write control for Parallel Slave Port (see $\overline{CS}$ and $\overline{RD}$ pins).
AN6				I	Analog	Analog input 6.
RE2/$\overline{CS}$/AN7	10	27	27			
RE2				I/O	ST	Digital I/O.
$\overline{CS}$				I	TTL	Chip select control for Parallel Slave Port (see related $\overline{RD}$ and $\overline{WR}$).
AN7				I	Analog	Analog input 7.
RE3	—	—	—	—	—	See $\overline{MCLR}$/V_{PP}/RE3 pin.
V_{SS}	12, 31	6, 30, 31	6, 29	P	—	Ground reference for logic and I/O pins.
V_{DD}	11, 32	7, 8, 28, 29	7, 28	P	—	Positive supply for logic and I/O pins.
NC	—	13	12,13, 33, 34	—	—	No connect.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

3: For the QFN package, it is recommended that the bottom pad be connected to V_{SS}.

2.4 RC Oscillator

For timing insensitive applications, the “RC” and “RCIO” device options offer additional cost savings. The actual oscillator frequency is a function of several factors:

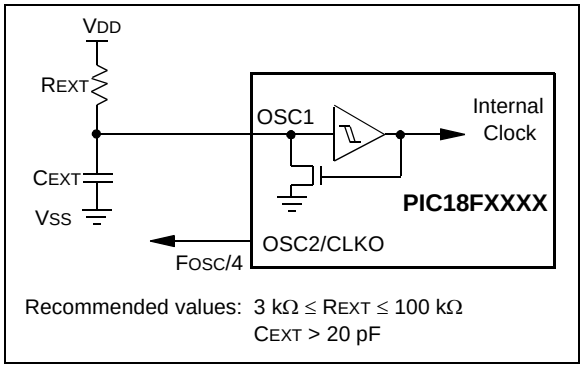
- supply voltage
- values of the external resistor (REXT) and capacitor (CEXT)
- operating temperature

Given the same device, operating voltage and temperature and component values, there will also be unit-to-unit frequency variations. These are due to factors such as:

- normal manufacturing variation
- difference in lead frame capacitance between package types (especially for low CEXT values)
- variations within the tolerance of limits of REXT and CEXT

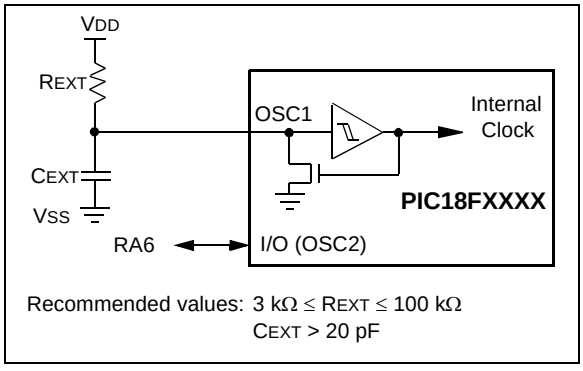
In the RC Oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic. Figure 2-5 shows how the R/C combination is connected.

FIGURE 2-5: RC OSCILLATOR MODE



The RCIO Oscillator mode (Figure 2-6) functions like the RC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6).

FIGURE 2-6: RCIO OSCILLATOR MODE



2.5 PLL Frequency Multiplier

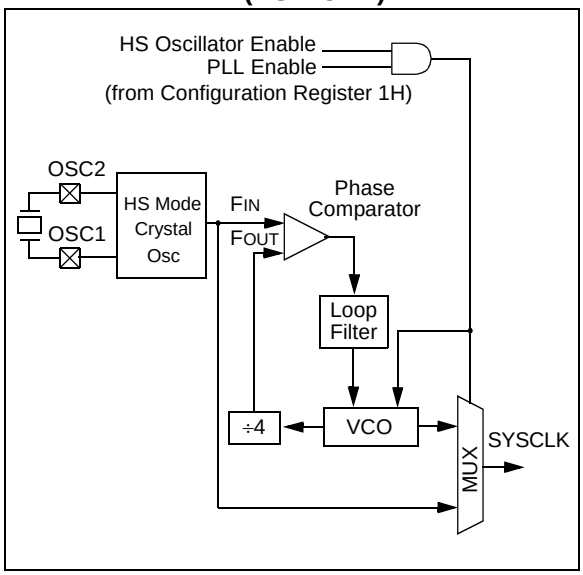
A Phase Locked Loop (PLL) circuit is provided as an option for users who wish to use a lower frequency oscillator circuit or to clock the device up to its highest rated frequency from a crystal oscillator. This may be useful for customers who are concerned with EMI due to high-frequency crystals or users who require higher clock speeds from an internal oscillator.

2.5.1 HSPLL OSCILLATOR MODE

The HSPLL mode makes use of the HS Oscillator mode for frequencies up to 10 MHz. A PLL then multiplies the oscillator output frequency by 4 to produce an internal clock frequency up to 40 MHz. The PLLEN bit is not available in this oscillator mode.

The PLL is only available to the crystal oscillator when the FOSC3:FOSC0 Configuration bits are programmed for HSPLL mode (= 0110).

FIGURE 2-7: PLL BLOCK DIAGRAM (HS MODE)



2.5.2 PLL AND INTOSC

The PLL is also available to the internal oscillator block in selected oscillator modes. In this configuration, the PLL is enabled in software and generates a clock output of up to 32 MHz. The operation of INTOSC with the PLL is described in **Section 2.6.4 “PLL in INTOSC Modes”**.

3.4.1 PRI_IDLE MODE

This mode is unique among the three low-power Idle modes, in that it does not disable the primary device clock. For timing sensitive applications, this allows for the fastest resumption of device operation with its more accurate primary clock source, since the clock source does not have to “warm-up” or transition from another oscillator.

PRI_IDLE mode is entered from PRI_RUN mode by setting the IDLEN bit and executing a SLEEP instruction. If the device is in another Run mode, set IDLEN first, then clear the SCS bits and execute SLEEP. Although the CPU is disabled, the peripherals continue to be clocked from the primary clock source specified by the FOSC3:FOSC0 Configuration bits. The OSTS bit remains set (see Figure 3-7).

When a wake event occurs, the CPU is clocked from the primary clock source. A delay of interval TCSD is required between the wake event and when code execution starts. This is required to allow the CPU to become ready to execute instructions. After the wake-up, the OSTS bit remains set. The IDLEN and SCS bits are not affected by the wake-up (see Figure 3-8).

3.4.2 SEC_IDLE MODE

In SEC_IDLE mode, the CPU is disabled but the peripherals continue to be clocked from the Timer1 oscillator. This mode is entered from SEC_RUN by setting the IDLEN bit and executing a SLEEP instruction. If the device is in another Run mode, set the IDLEN bit first, then set the SCS1:SCS0 bits to ‘01’ and execute SLEEP. When the clock source is switched to the Timer1 oscillator, the primary oscillator is shut down, the OSTS bit is cleared and the T1RUN bit is set.

When a wake event occurs, the peripherals continue to be clocked from the Timer1 oscillator. After an interval of TCSD following the wake event, the CPU begins executing code being clocked by the Timer1 oscillator. The IDLEN and SCS bits are not affected by the wake-up; the Timer1 oscillator continues to run (see Figure 3-8).

Note:	The Timer1 oscillator should already be running prior to entering SEC_IDLE mode. If the T1OSCEN bit is not set when the SLEEP instruction is executed, the SLEEP instruction will be ignored and entry to SEC_IDLE mode will not occur. If the Timer1 oscillator is enabled but not yet running, peripheral clocks will be delayed until the oscillator has started. In such situations, initial oscillator operation is far from stable and unpredictable operation may result.

FIGURE 3-7: TRANSITION TIMING FOR ENTRY TO IDLE MODE

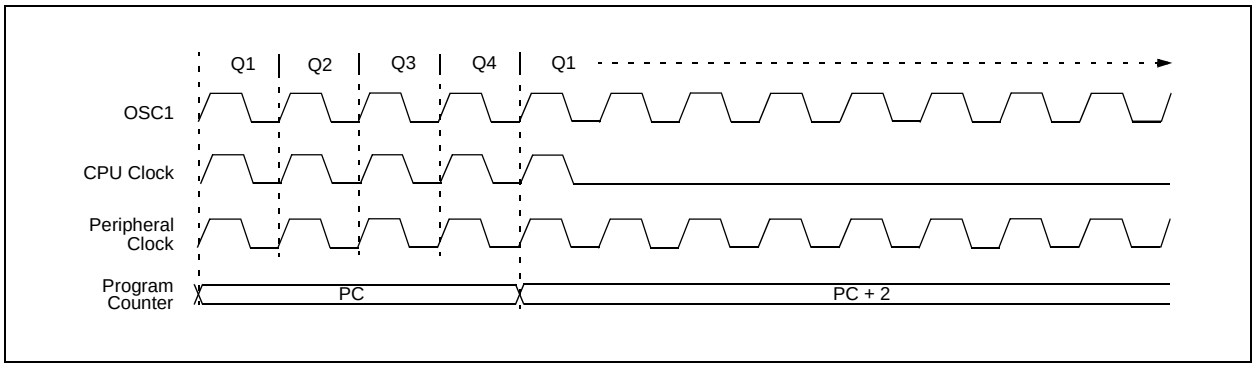


FIGURE 3-8: TRANSITION TIMING FOR WAKE FROM IDLE TO RUN MODE

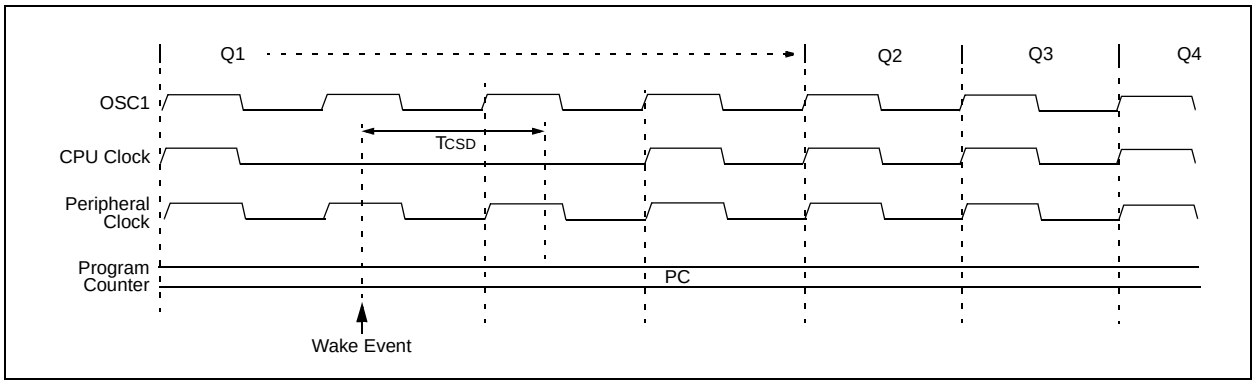


FIGURE 4-6: SLOW RISE TIME ($\overline{MCLR}$ TIED TO V_{DD}, V_{DD} RISE > T_{PWRT})

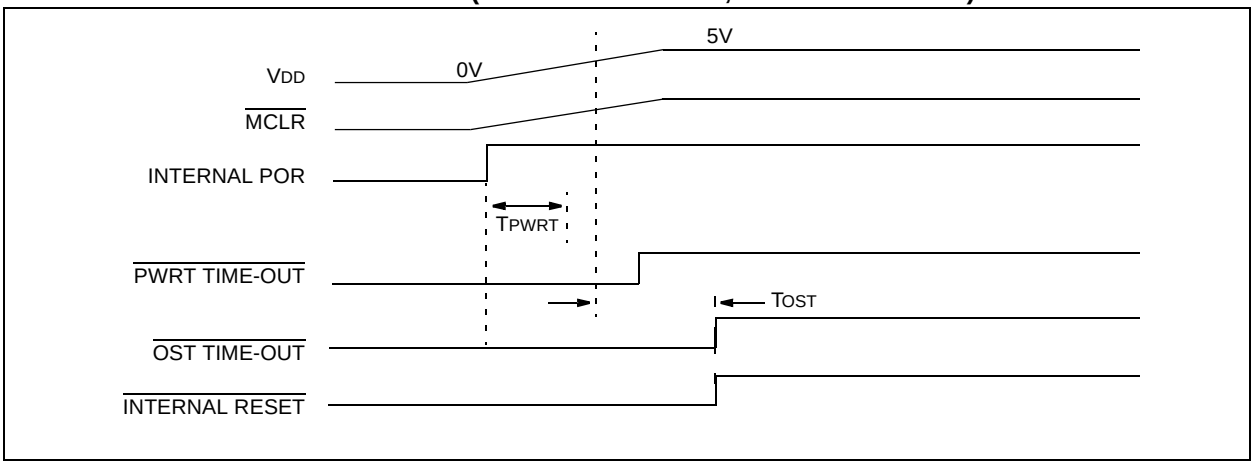
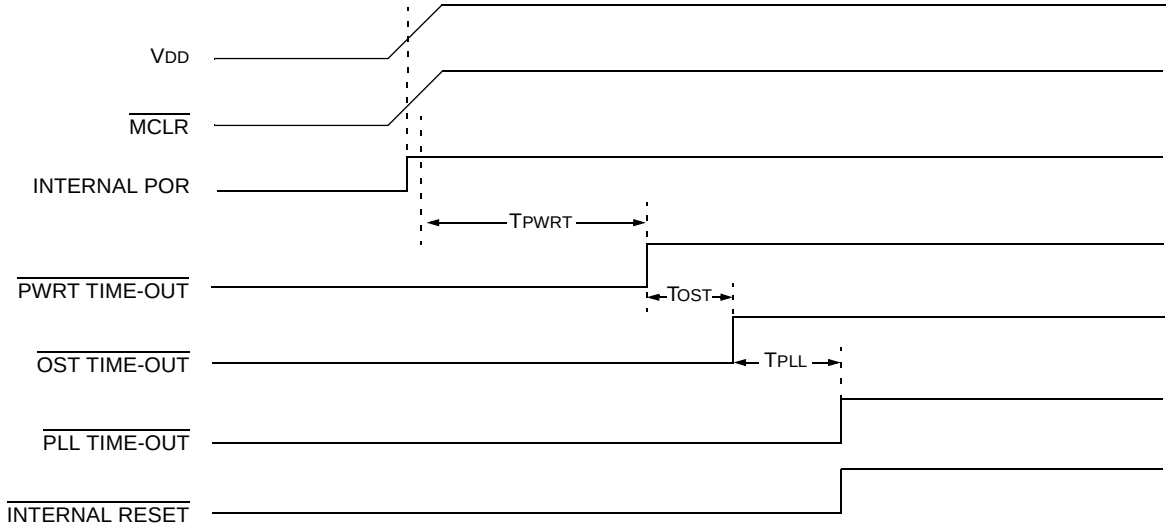


FIGURE 4-7: TIME-OUT SEQUENCE ON POR W/PLL ENABLED ($\overline{MCLR}$ TIED TO V_{DD})



Note: T_{OST} = 1024 clock cycles.
$T_{PLL} \approx$ 2 ms max. First three stages of the PWRT timer.

7.0 FLASH PROGRAM MEMORY

The Flash program memory is readable, writable and erasable during normal operation over the entire VDD range.

A read from program memory is executed on one byte at a time. A write to program memory is executed on blocks of 64 bytes at a time. Program memory is erased in blocks of 64 bytes at a time. A bulk erase operation may not be issued from user code.

Writing or erasing program memory will cease instruction fetches until the operation is complete. The program memory cannot be accessed during the write or erase, therefore, code cannot execute. An internal programming timer terminates program memory writes and erases.

A value written to program memory does not need to be a valid instruction. Executing a program memory location that forms an invalid instruction results in a NOP.

7.1 Table Reads and Table Writes

In order to read and write program memory, there are two operations that allow the processor to move bytes between the program memory space and the data RAM:

- Table Read (TBLRD)
- Table Write (TBLWT)

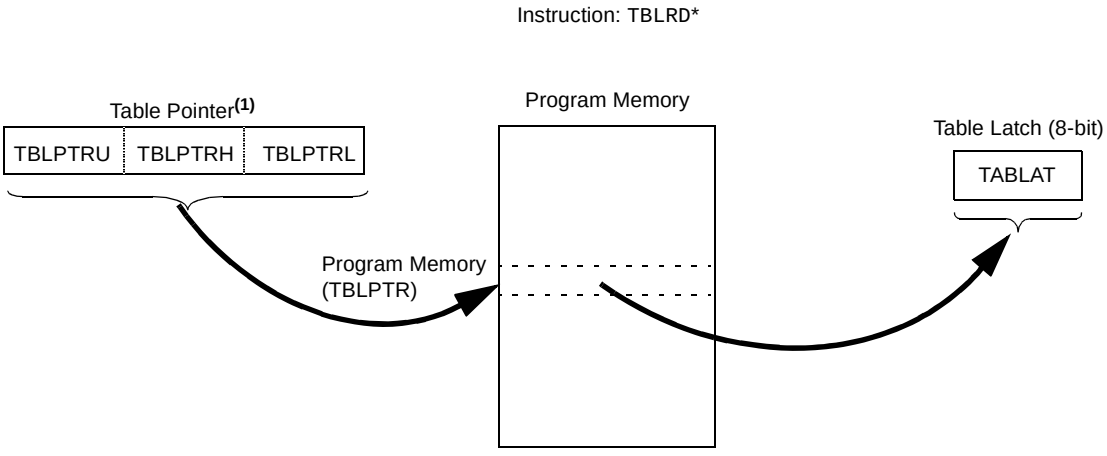
The program memory space is 16 bits wide, while the data RAM space is 8 bits wide. Table reads and table writes move data between these two memory spaces through an 8-bit register (TABLAT).

Table read operations retrieve data from program memory and place it into the data RAM space. Figure 7-1 shows the operation of a table read with program memory and data RAM.

Table write operations store data from the data memory space into holding registers in program memory. The procedure to write the contents of the holding registers into program memory is detailed in **Section 7.5 “Writing to Flash Program Memory”**. Figure 7-2 shows the operation of a table write with program memory and data RAM.

Table operations work with byte entities. A table block containing data, rather than program instructions, is not required to be word aligned. Therefore, a table block can start and end at any byte address. If a table write is being used to write executable code into program memory, program instructions will need to be word-aligned.

FIGURE 7-1: TABLE READ OPERATION



Note 1: Table Pointer register points to a byte in program memory.

REGISTER 10-2: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-1	R/W-1	R/W-1	R/W-1	U-0	R/W-1	U-0	R/W-1
$\overline{\text{RBPU}}$	INTEDG0	INTEDG1	INTEDG2	—	TMR0IP	—	RBIP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **$\overline{\text{RBPU}}$:** PORTB Pull-up Enable bit
1 = All PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6 **INTEDG0:** External Interrupt 0 Edge Select bit
1 = Interrupt on rising edge
0 = Interrupt on falling edge

bit 5 **INTEDG1:** External Interrupt 1 Edge Select bit
1 = Interrupt on rising edge
0 = Interrupt on falling edge

bit 4 **INTEDG2:** External Interrupt 2 Edge Select bit
1 = Interrupt on rising edge
0 = Interrupt on falling edge

bit 3 **Unimplemented:** Read as ‘0’

bit 2 **TMR0IP:** TMR0 Overflow Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **RBIP:** RB Port Change Interrupt Priority bit
1 = High priority
0 = Low priority

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global interrupt enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

TABLE 15-3: REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, TIMER1 AND TIMER3

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	49
RCON	IPEN	SBOREN(1)	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	48
PIR1	PSPIF(2)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	52
PIE1	PSPIE(2)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	52
IPR1	PSPIP(2)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	52
PIR2	OSCFIF	CMIF	—	EEIF	BCLIF	HLVDIF	TMR3IF	CCP2IF	52
PIE2	OSCFIE	CMIE	—	EEIE	BCLIE	HLVDIE	TMR3IE	CCP2IE	52
IPR2	OSCFIP	CMIP	—	EEIP	BCLIP	HLVDIP	TMR3IP	CCP2IP	52
TRISB	PORTB Data Direction Control Register								52
TRISC	PORTC Data Direction Control Register								52
TMR1L	Timer1 Register Low Byte								50
TMR1H	Timer1 Register High Byte								50
T1CON	RD16	T1RUN	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	50
TMR3H	Timer3 Register High Byte								51
TMR3L	Timer3 Register Low Byte								51
T3CON	RD16	T3CCP2	T3CKPS1	T3CKPS0	T3CCP1	$\overline{T3SYNC}$	TMR3CS	TMR3ON	51
CCPR1L	Capture/Compare/PWM Register 1 Low Byte								51
CCPR1H	Capture/Compare/PWM Register 1 High Byte								51
CCP1CON	P1M1(2)	P1M0(2)	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	51
CCPR2L	Capture/Compare/PWM Register 2 Low Byte								51
CCPR2H	Capture/Compare/PWM Register 2 High Byte								51
CCP2CON	—	—	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	51

Legend: — = unimplemented, read as '0'. Shaded cells are not used by Capture/Compare, Timer1 or Timer3.

Note 1: The SBOREN bit is only available when the BOREN1:BOREN0 Configuration bits = 01; otherwise, it is disabled and reads as '0'. See **Section 4.4 "Brown-out Reset (BOR)"**.

2: These bits are unimplemented on 28-pin devices and read as '0'.

17.3.2 OPERATION

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits (SSPCON1<5:0> and SSPSTAT<7:6>). These control bits allow the following to be specified:

- Master mode (SCK is the clock output)
- Slave mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Data Input Sample Phase (middle or end of data output time)
- Clock Edge (output data on rising/falling edge of SCK)
- Clock Rate (Master mode only)
- Slave Select mode (Slave mode only)

The MSSP consists of a transmit/receive shift register (SSPSR) and a buffer register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR until the received data is ready. Once the 8 bits of data have been received, that byte is moved to the SSPBUF register. Then, the Buffer Full detect bit, BF (SSPSTAT<0>) and the interrupt flag bit, SSPIF, are set. This double-buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored and the write collision detect bit, WCOL (SSPCON1<7>), will be set. User software must clear the WCOL bit so that it can be determined if the following write(s) to the SSPBUF register completed successfully.

When the application software is expecting to receive valid data, the SSPBUF should be read before the next byte of data to transfer is written to the SSPBUF. The Buffer Full bit, BF (SSPSTAT<0>), indicates when SSPBUF has been loaded with the received data (transmission is complete). When the SSPBUF is read, the BF bit is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally, the MSSP interrupt is used to determine when the transmission/reception has completed. The SSPBUF must be read and/or written. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur. Example 17-1 shows the loading of the SSPBUF (SSPSR) for data transmission.

The SSPSR is not directly readable or writable and can only be accessed by addressing the SSPBUF register. Additionally, the MSSP status register (SSPSTAT) indicates the various status conditions.

Note:	The SSPBUF register cannot be used with read-modify-write instructions such as BCF, BTFSC and COMF, etc.

Note:	To avoid lost data in Master mode, a read of the SSPBUF must be performed to clear the Buffer Full (BF) detect bit (SSPSTAT<0>) between each transmission.

EXAMPLE 17-1: LOADING THE SSPBUF (SSPSR) REGISTER

```
LOOP    BTFSS   SSPSTAT, BF     ;Has data been received (transmit complete)?
        BRA     LOOP            ;No
        MOVF    SSPBUF, W       ;WREG reg = contents of SSPBUF
        MOVWF   RXDATA          ;Save in user RAM, if data is meaningful
        MOVF    TXDATA, W       ;W reg = contents of TXDATA
        MOVWF   SSPBUF          ;New data to xmit
```

NOTES:

NOTES:

REGISTER 23-4: CONFIG3H: CONFIGURATION REGISTER 3 HIGH (BYTE ADDRESS 300005h)

R/P-1	U-0	U-0	U-0	U-0	R/P-0	R/P-1	R/P-1
MCLRE	—	—	—	—	LPT1OSC	PBADEN	CCP2MX
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as ‘0’
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7 **MCLRE:** $\overline{\text{MCLR}}$ Pin Enable bit
1 = $\overline{\text{MCLR}}$ pin enabled; RE3 input pin disabled
0 = RE3 input pin enabled; $\overline{\text{MCLR}}$ disabled

bit 6-3 **Unimplemented:** Read as ‘0’

bit 2 **LPT1OSC:** Low-Power Timer1 Oscillator Enable bit
1 = Timer1 configured for low-power operation
0 = Timer1 configured for higher power operation

bit 1 **PBADEN:** PORTB A/D Enable bit
(Affects ADCON1 Reset state. ADCON1 controls PORTB<4:0> pin configuration.)
1 = PORTB<4:0> pins are configured as analog input channels on Reset
0 = PORTB<4:0> pins are configured as digital I/O on Reset

bit 0 **CCP2MX:** CCP2 MUX bit
1 = CCP2 input/output is multiplexed with RC1
0 = CCP2 input/output is multiplexed with RB3

REGISTER 23-5: CONFIG4L: CONFIGURATION REGISTER 4 LOW (BYTE ADDRESS 300006h)

R/P-1	R/P-0	U-0	U-0	U-0	R/P-1	U-0	R/P-1
$\overline{\text{DEBUG}}$	XINST	—	—	—	LVP	—	STVREN
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as ‘0’
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7 $\overline{\textbf{DEBUG}}$**:** Background Debugger Enable bit
1 = Background debugger disabled, RB6 and RB7 configured as general purpose I/O pins
0 = Background debugger enabled, RB6 and RB7 are dedicated to In-Circuit Debug

bit 6 **XINST:** Extended Instruction Set Enable bit
1 = Instruction set extension and Indexed Addressing mode enabled
0 = Instruction set extension and Indexed Addressing mode disabled (Legacy mode)

bit 5-3 **Unimplemented:** Read as ‘0’

bit 2 **LVP:** Single-Supply ICSP™ Enable bit
1 = Single-Supply ICSP enabled
0 = Single-Supply ICSP disabled

bit 1 **Unimplemented:** Read as ‘0’

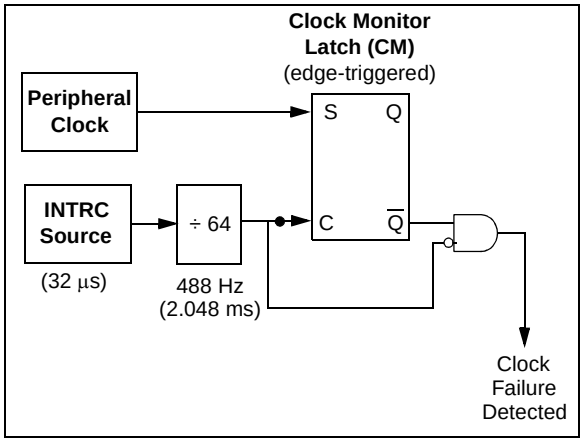
bit 0 **STVREN:** Stack Full/Underflow Reset Enable bit
1 = Stack full/underflow will cause Reset
0 = Stack full/underflow will not cause Reset

23.4 Fail-Safe Clock Monitor

The Fail-Safe Clock Monitor (FSCM) allows the microcontroller to continue operation in the event of an external oscillator failure by automatically switching the device clock to the internal oscillator block. The FSCM function is enabled by setting the FCMEN Configuration bit.

When FSCM is enabled, the INTRC oscillator runs at all times to monitor clocks to peripherals and provide a backup clock in the event of a clock failure. Clock monitoring (shown in Figure 23-3) is accomplished by creating a sample clock signal, which is the INTRC output divided by 64. This allows ample time between FSCM sample clocks for a peripheral clock edge to occur. The peripheral device clock and the sample clock are presented as inputs to the Clock Monitor latch (CM). The CM is set on the falling edge of the device clock source, but cleared on the rising edge of the sample clock.

FIGURE 23-3: FSCM BLOCK DIAGRAM



Clock failure is tested for on the falling edge of the sample clock. If a sample clock falling edge occurs while CM is still set, a clock failure has been detected (Figure 23-4). This causes the following:

- the FSCM generates an oscillator fail interrupt by setting bit, OSCFIF (PIR2<7>);
- the device clock source is switched to the internal oscillator block (OSCCON is not updated to show the current clock source – this is the fail-safe condition); and
- the WDT is reset.

During switchover, the postscaler frequency from the internal oscillator block may not be sufficiently stable for timing sensitive applications. In these cases, it may be desirable to select another clock configuration and enter an alternate power-managed mode. This can be done to attempt a partial recovery or execute a controlled shutdown. See **Section 3.1.4 "Multiple Sleep Commands"** and **Section 23.3.1 "Special Considerations for Using Two-Speed Start-up"** for more details.

To use a higher clock speed on wake-up, the INTOSC or postscaler clock sources can be selected to provide a higher clock speed by setting bits, IRCF2:IRCF0, immediately after Reset. For wake-ups from Sleep, the INTOSC or postscaler clock sources can be selected by setting the IRCF2:IRCF0 bits prior to entering Sleep mode.

The FSCM will detect failures of the primary or secondary clock sources only. If the internal oscillator block fails, no failure would be detected, nor would any action be possible.

23.4.1 FSCM AND THE WATCHDOG TIMER

Both the FSCM and the WDT are clocked by the INTRC oscillator. Since the WDT operates with a separate divider and counter, disabling the WDT has no effect on the operation of the INTRC oscillator when the FSCM is enabled.

As already noted, the clock source is switched to the INTOSC clock when a clock failure is detected. Depending on the frequency selected by the IRCF2:IRCF0 bits, this may mean a substantial change in the speed of code execution. If the WDT is enabled with a small prescale value, a decrease in clock speed allows a WDT time-out to occur and a subsequent device Reset. For this reason, fail-safe clock events also reset the WDT and postscaler, allowing it to start timing from when execution speed was changed and decreasing the likelihood of an erroneous time-out.

23.4.2 EXITING FAIL-SAFE OPERATION

The fail-safe condition is terminated by either a device Reset or by entering a power-managed mode. On Reset, the controller starts the primary clock source specified in Configuration Register 1H (with any required start-up delays that are required for the oscillator mode, such as OST or PLL timer). The INTOSC multiplexer provides the device clock until the primary clock source becomes ready (similar to a Two-Speed Start-up). The clock source is then switched to the primary clock (indicated by the OSTS bit in the OSCCON register becoming set). The Fail-Safe Clock Monitor then resumes monitoring the peripheral clock.

The primary clock source may never become ready during start-up. In this case, operation is clocked by the INTOSC multiplexer. The OSCCON register will remain in its Reset state until a power-managed mode is entered.

POP **Pop Top of Return Stack**

Syntax: POP

Operands: None

Operation: (TOS) → bit bucket

Status Affected: None

Encoding:

0000	0000	0000	0110

Description: The TOS value is pulled off the return stack and is discarded. The TOS value then becomes the previous value that was pushed onto the return stack. This instruction is provided to enable the user to properly manage the return stack to incorporate a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	POP TOS value	No operation

Example:
```
POP
GOTO    NEW
```
Before Instruction
TOS = 0031A2h
Stack (1 level down) = 014332h

After Instruction
TOS = 014332h
PC = NEW

PUSH **Push Top of Return Stack**

Syntax: PUSH

Operands: None

Operation: (PC + 2) → TOS

Status Affected: None

Encoding:

0000	0000	0000	0101

Description: The PC + 2 is pushed onto the top of the return stack. The previous TOS value is pushed down on the stack. This instruction allows implementing a software stack by modifying TOS and then pushing it onto the return stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	PUSH PC + 2 onto return stack	No operation	No operation

Example:
```
PUSH
```
Before Instruction
TOS = 345Ah
PC = 0124h

After Instruction
PC = 0126h
TOS = 0126h
Stack (1 level down) = 345Ah

SUBFSR **Subtract Literal from FSR**

Syntax: SUBFSR f, k

Operands: $0 \le k \le 63$

$f \in [0, 1, 2]$

Operation: $FSR(f - k) \rightarrow FSR(f)$

Status Affected: None

Encoding:

1110	1001	ffkk	kkkk

Description: The 6-bit literal 'k' is subtracted from the contents of the FSR specified by 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: SUBFSR 2, 23h

Before Instruction
FSR2 = 03FFh

After Instruction
FSR2 = 03DCh

SUBULNK **Subtract Literal from FSR2 and Return**

Syntax: SUBULNK k

Operands: $0 \le k \le 63$

Operation: $FSR2 - k \rightarrow FSR2$,
$(TOS) \rightarrow PC$

Status Affected: None

Encoding:

1110	1001	11kk	kkkk

Description: The 6-bit literal 'k' is subtracted from the contents of the FSR2. A RETURN is then executed by loading the PC with the TOS. The instruction takes two cycles to execute; a NOP is performed during the second cycle.
This may be thought of as a special case of the SUBFSR instruction, where f = 3 (binary '11'); it operates only on FSR2.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination
No Operation	No Operation	No Operation	No Operation

Example: SUBULNK 23h

Before Instruction
FSR2 = 03FFh
PC = 0100h

After Instruction
FSR2 = 03DCh
PC = (TOS)

26.2 DC Characteristics: Power-Down and Supply Current PIC18F2525/2620/4525/4620 (Industrial) PIC18LF2525/2620/4525/4620 (Industrial) (Continued)

PIC18LF2525/2620/4525/4620 (Industrial)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC18F2525/2620/4525/4620 (Industrial, Extended)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Device	Typ	Max	Units	Conditions		
	Supply Current (IDD)(2)						
	PIC18LFX525/X620	13	25	µA	-40°C	VDD = 2.0V	FOSC = 31 kHz (**RC_RUN** mode, INTRC source)
		13	22	µA	+25°C		
		14	25	µA	+85°C		
	PIC18LFX525/X620	42	61	µA	-40°C	VDD = 3.0V	
		34	46	µA	+25°C		
		28	45	µA	+85°C		
	All devices	103	160	µA	-40°C	VDD = 5.0V	
		82	130	µA	+25°C		
		67	120	µA	+85°C		
	Extended devices only	71	230	µA	+125°C		
	PIC18LFX525/X620	320	440	µA	-40°C	VDD = 2.0V	FOSC = 1 MHz (**RC_RUN** mode, INTOSC source)
		330	440	µA	+25°C		
		330	440	µA	+85°C		
	PIC18LFX525/X620	630	800	µA	-40°C	VDD = 3.0V	
		590	720	µA	+25°C		
		570	700	µA	+85°C		
	All devices	1.2	1.6	mA	-40°C	VDD = 5.0V	
		1.0	1.5	mA	+25°C		
		1.0	1.5	mA	+85°C		
	Extended devices only	1.0	1.5	mA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

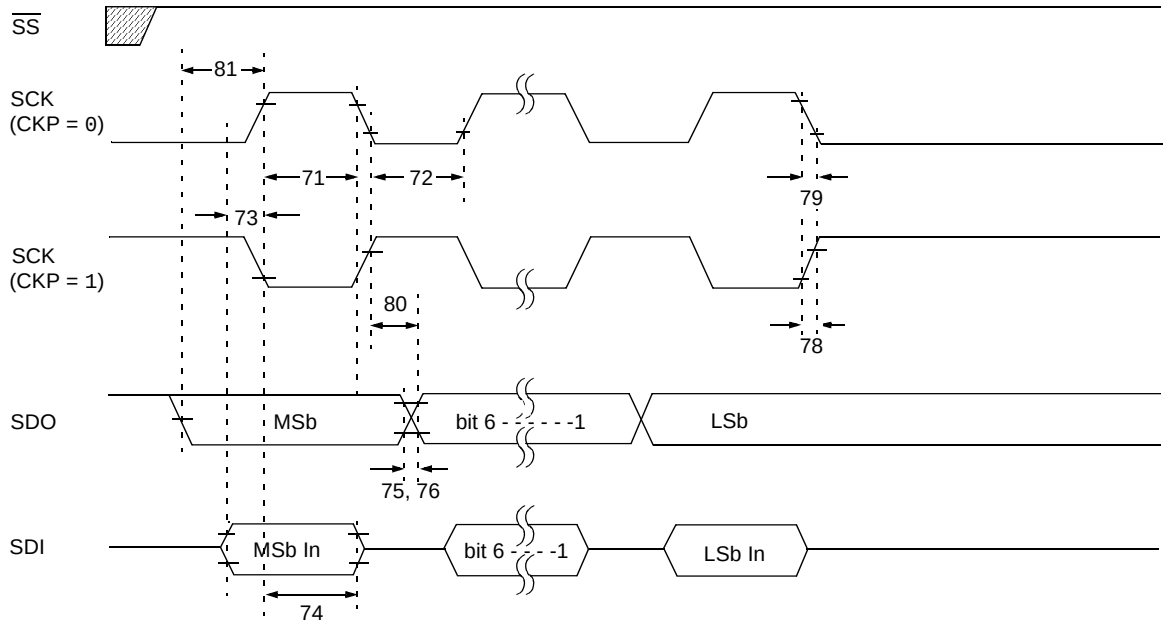
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;

$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

FIGURE 26-14: EXAMPLE SPI MASTER MODE TIMING (CKE = 1)



Note: Refer to Figure 26-5 for load conditions.

TABLE 26-15: EXAMPLE SPI MODE REQUIREMENTS (MASTER MODE, CKE = 1)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
71	TscH	SCK Input High Time (Slave mode)	Continuous	1.25 TCY + 30	—	ns	
71A			Single Byte	40	—	ns	**(Note 1)**
72	TscL	SCK Input Low Time (Slave mode)	Continuous	1.25 TCY + 30	—	ns	
72A			Single Byte	40	—	ns	**(Note 1)**
73	TdiV2scH, TdiV2scL	Setup Time of SDI Data Input to SCK Edge		20	—	ns	
73A	Tb2b	Last Clock Edge of Byte 1 to the 1st Clock Edge of Byte 2		1.5 TCY + 40	—	ns	**(Note 2)**
74	TscH2diL, TscL2diL	Hold Time of SDI Data Input to SCK Edge		40	—	ns	
75	TdoR	SDO Data Output Rise Time	PIC18**F**XXXX	—	25	ns	
			PIC18**LF**XXXX		45	ns	VDD = 2.0V
76	TdoF	SDO Data Output Fall Time		—	25	ns	
78	TscR	SCK Output Rise Time (Master mode)	PIC18**F**XXXX	—	25	ns	
			PIC18**LF**XXXX		45	ns	VDD = 2.0V
79	TscF	SCK Output Fall Time (Master mode)		—	25	ns	
80	TscH2doV, TscL2doV	SDO Data Output Valid after SCK Edge	PIC18**F**XXXX	—	50	ns	
			PIC18**LF**XXXX		100	ns	VDD = 2.0V
81	TdoV2scH, TdoV2scL	SDO Data Output Setup to SCK Edge		TCY	—	ns	

Note 1: Requires the use of Parameter #73A.

2: Only if Parameter #71A and #72A are used.

TABLE 26-21: MASTER SSP I²C™ BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
101	TLOW	Clock Low Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
102	TR	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
103	TF	SDA and SCL Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
90	TSU:STA	Start Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	Only relevant for Repeated Start condition
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
91	THD:STA	Start Condition Hold Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	After this period, the first clock pulse is generated
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	ms	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(1)	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	ms	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	ms	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: Maximum pin capacitance = 10 pF for all I²C pins.

2: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but parameter 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line, parameter 102 + parameter 107 = 1000 + 250 = 1250 ns (for 100 kHz mode), before the SCL line is released.

FIGURE 27-31: VIN (ST) vs. VDD, 25°C (-40°C TO +125°C)

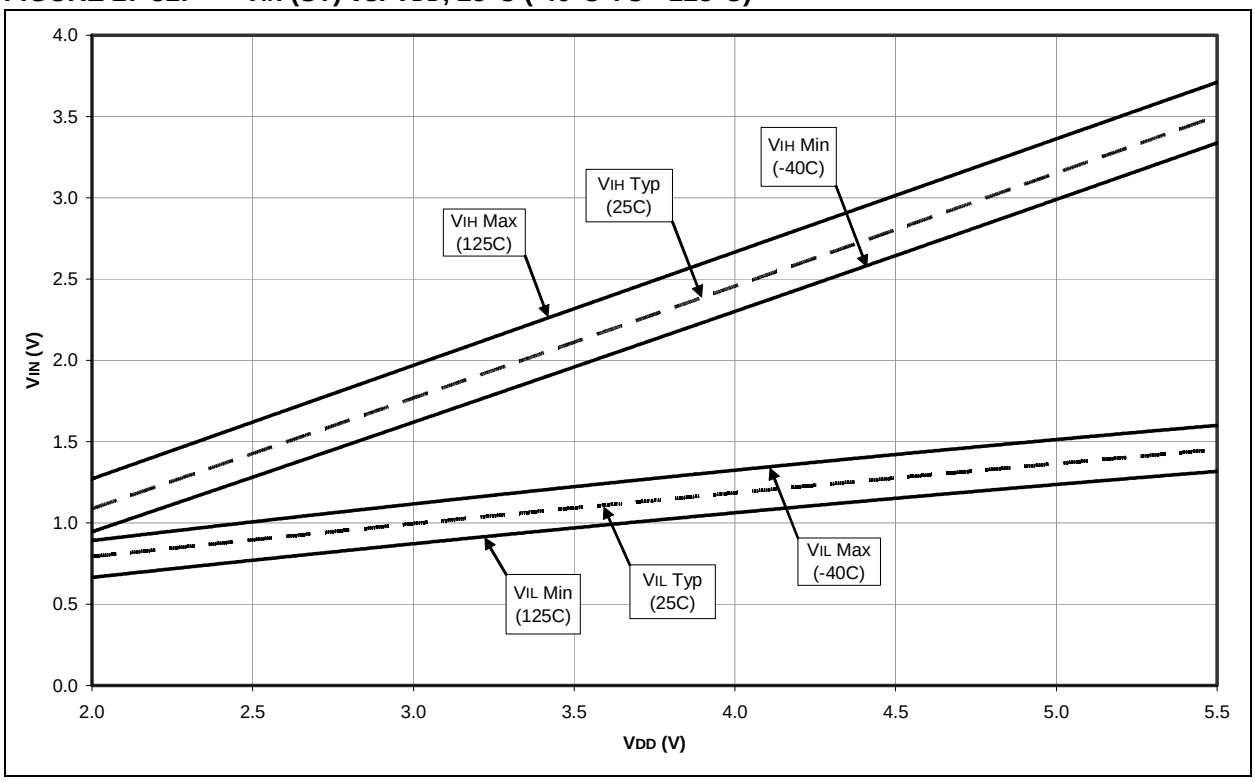
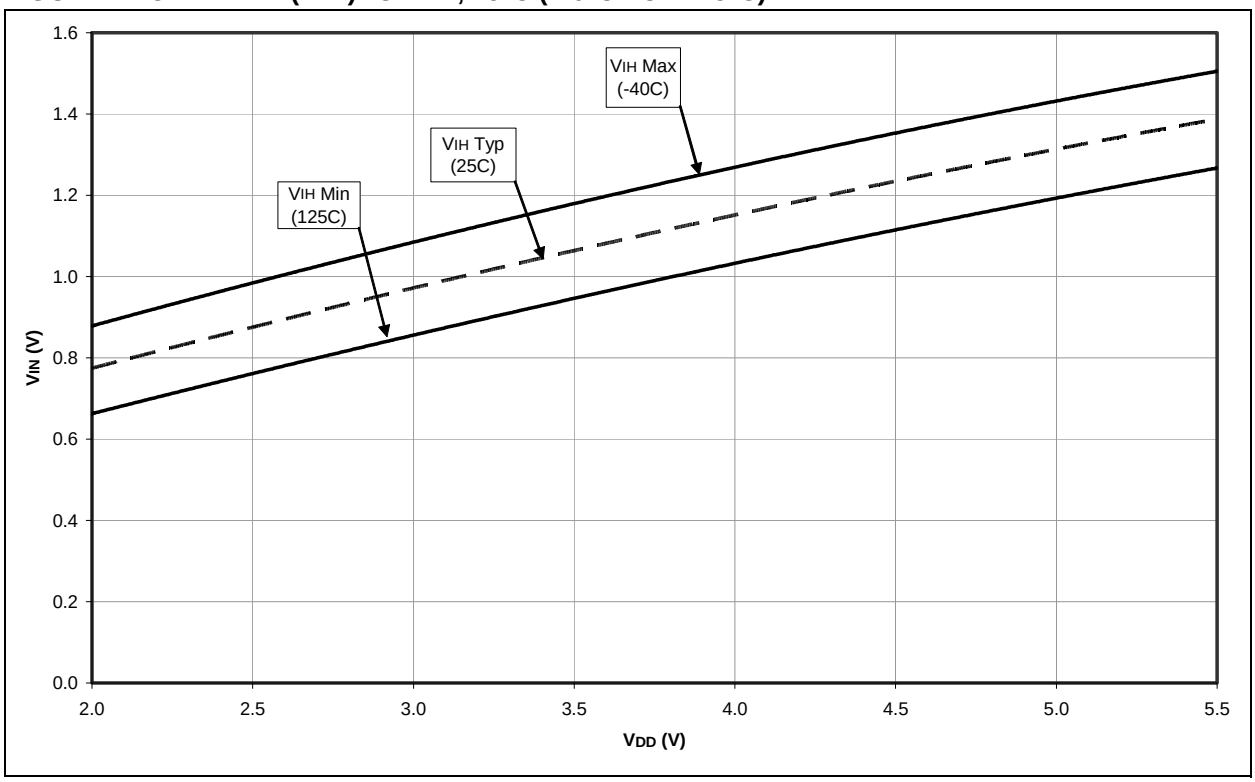
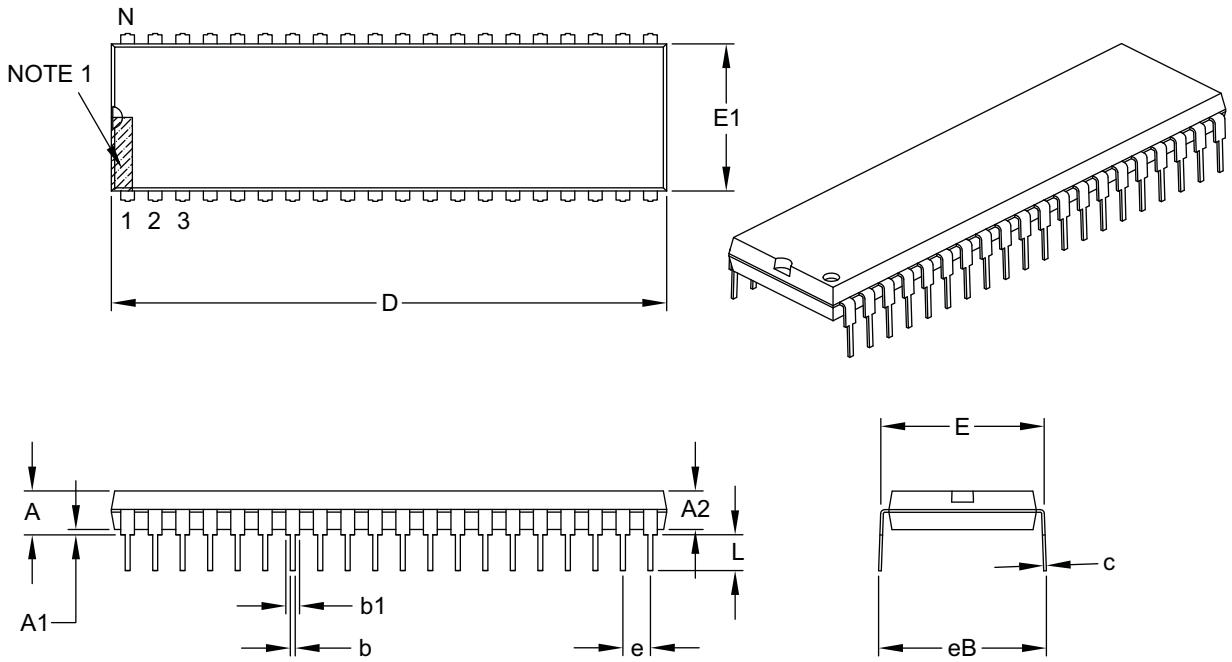


FIGURE 27-32: VIN (TTL) vs. VDD, 25°C (-40°C TO +125°C)



40-Lead Plastic Dual In-Line (P) – 600 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		40	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.250
Molded Package Thickness	A2	.125	–	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.590	–	.625
Molded Package Width	E1	.485	–	.580
Overall Length	D	1.980	–	2.095
Tip to Seating Plane	L	.115	–	.200
Lead Thickness	c	.008	–	.015
Upper Lead Width	b1	.030	–	.070
Lower Lead Width	b	.014	–	.023
Overall Row Spacing §	eB	–	–	.700

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-016B